

JG12 Rec'd PCT/PTC 27 SEP 2005

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| INFORMATION DISCLOSURE STATEMENT |  | Atty. Docket No.<br>ABE-034        | Serial No.<br>10/55076<br>Not assigned |
| PTO-1449                         |  | Applicant:<br>Eiji KAMIYAMA et al. |  |
|                                  |  | Filing Date:<br>September 27, 2005 | Group: 1763<br>Not assigned            |

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| /RC/               | UA | 5,882,987 A  | 03/16/99 | Srikrishnan  | 438   | 458       |                            |
| /RC/               | UB | 6,140,210 A  | 10/31/00 | Aga et al.   | 438   | 458       |                            |
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| /RC/               | UD | 5,374,564 A  | 12/20/94 | Bruel        | 437   | 24        |                            |
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| /RC/               | FB | 11-102848 A   | 04/13/99 | JP      | Abstract                   |
| /RC/               | FC | 2000-124092 A | 04/28/00 | JP      | Abstract                   |
| /RC/               | FD | 2003-17723 A  | 01/17/03 | JP      | Abstract & Translation     |
| /RC/               | FE | 2004-80035 A  | 03/11/04 | JP      | Abstract & Translation     |
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| /RC/               | DB | Tong, Q.Y. et al., "Semiconductor Wafer Bonding: Science and Technology"; November, 1998:printout of website <a href="http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813,descCd-description.html?print=true">http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813,descCd-description.html?print=true</a> . |
|                    | DC |  |

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| Examiner: | /Roberts Culbert/ | Date Considered: | 08/05/2007 |
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| INFORMATION DISCLOSURE STATEMENT   |  | Atty. Docket No.<br>ABE-034        | Serial No.<br>Not assigned |
| PTO-1449                           |  | Applicant:<br>Eiji KAMIYAMA et al: |                            |
| Filing Date:<br>September 27, 2005 |  | Group:<br>Not assigned             |                            |

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| /RC/               | UB | 6,140,210 A  | 10/31/00 | Aga et al.   | 438   | 458       |                            |
| /RC/               | UC | 6,372,609 B1 | 04/16/02 | Aga et al.   | 438   | 459       |                            |
| /RC/               | UD | 5,374,564 A  | 12/20/94 | Bruel        | 437   | 24        |                            |
| /RC/               | UE | 6,020,252 A  | 02/01/00 | Aspar et al. | 438   | 458       |                            |
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|                    | UG |              |          |              |       |           |                            |

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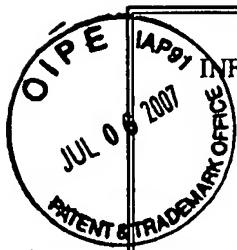
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| /RC/               | FD | 2003-17723 A  | 01/17/03 | JP      | Abstract & Translation     |
| /RC/               | FE | 2004-80035 A  | 03/11/04 | JP      | Abstract & Translation     |
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| Examiner: | /Roberts Culbert/ | Date Considered: | 08/05/2007 |
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**INFORMATION DISCLOSURE STATEMENT**

PTO-1449

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|------------------------------------|--------------------------|
| Atty. Docket No.<br>ABE-034        | Serial No.<br>10/550,761 |
| Applicant:<br>Eiji KAMIYAMA et al. |                          |
| Filing Date:<br>January 9, 2006    | Group:<br>2012 1763      |

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|                    | UD |              |          |            |       |           |                            |
|                    | UE |              |          |            |       |           |                            |
|                    | UF |              |          |            |       |           |                            |
|                    | UG |              |          |            |       |           |                            |

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Examiner: /Roberts Culbert/ Date Considered: 08/05/2007

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